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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

What is claimed is:

1. (Currently Amended) A solid substrate for a biochip comprising a compound represented by Formula 1 below in which a compound of Formula 3 below vertically passes through a cavity of cucurbituril or its derivative of Formula 2 below:

$$Y_1 - R_1 - X_1 - R_2 - X_2 - R_3 - Y_2$$
(1)

wherein R_1 , R_2 , and R_3 are each independently saturated or unsaturated linear C_2 - C_{10} alkylene, ethyleneglycol oligomer, 1,4-substituted benzene, or 1,4-substituted pyridine; X_1 and X_2 are each independently a positively charged functional group for ion-dipole interaction with an oxygen atom of cucurbituril or its derivative of Formula 2; Y_1 is a functional group for a linkage with a biomaterial comprising a gene or a protein; and Y_2 is a functional group for a linkage with a solid substrate, wherein the compound of Formula 1 provides a linkage layer with a predetermined spacing in the biochip by being bonded to the solid substrate.

- 2. (Currently Amended) The compound solid substrate of claim 1, wherein X_1 and X_2 are each independently secondary ammonium, 1,4-substituted pyridinum, or benzyl ammonium; and Y_1 and Y_2 are each independently a primary amine group, an amide group, an acrylamine group, an alkylester group, an aldehyde group, a carboxyl group, an alkoxysilane group, a halogenated acyl group, a hydroxyl group, a thiol group, a halogen group, a cyan group, an isocyan group, or an isothiocyan group.
 - 3. (Currently Amended) The compound solid substrate of claim 1, which

is selected from the group consisting of compounds represented by Formulae 5 through 13:

4. (Cancelled)

- 5. (Currently Amended) The solid substrate of claim [4] 1, wherein the compound of Formula 1 is present in a density of 0.05 to 0.6 compounds/nm².
- 6. (Currently Amended) The solid substrate of claim [4] 1, which is a glass, a silicon wafer, an indium tin oxide (ITO) glass, an aluminum oxide substrate, or a titanium dioxide substrate.

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- 7. (Previously Presented) A gene chip comprising the solid substrate of claim 1.
- 8. (Previously Presented) A protein chip comprising the solid substrate of claim 1.
- 9. (Previously Presented) A sensor for biomaterial assay comprising the solid substrate of claim 1.
- 10. (New) The solid substrate of claim 1, wherein the biochip is selected from the group consisting of a gene chip, a protein chip and a sensor for biomaterial assay.
- 11. (New) The solid substrate of claim 1, wherein the compound of Formula 1 is bonded to the solid substrate via a covalent bond or a non-covalent bond.
- 12. (New) The solid substrate of claim 1, wherein a compound of Formula 3

$$Y_1 - R_1 - X_1 - R_2 - X_2 - R_3 - Y_2$$
 (3)

(wherein R_1 , R_2 , R_3 , X_1 , X_2 , Y_1 , and Y_2 are as defined in Formula 1 above) vertically passes through a cavity of cucurbituril or its derivative of Formula 2

wherein n is an integer of 4 to 20; and R_4 and R_5 are each independently hydrogen, an alkenyloxy group with an unsaturated bond end and a substituted or unsubstituted alkyl moiety of C_1 - C_{20} , a carboxyalkylsulfinyloxy group with a substituted or unsubstituted alkyl moiety of C_1 - C_{20} , a carboxyalkyloxy group with a

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substituted or unsubstituted alkyl moiety of C_2 - C_8 , an aminoalkyloxy group with a substituted or unsubstituted alkyl moiety of C_2 - C_8 , or a hydroxyalkyloxy group with a substituted or unsubstituted alkyl moiety of C_2 - C_8 .